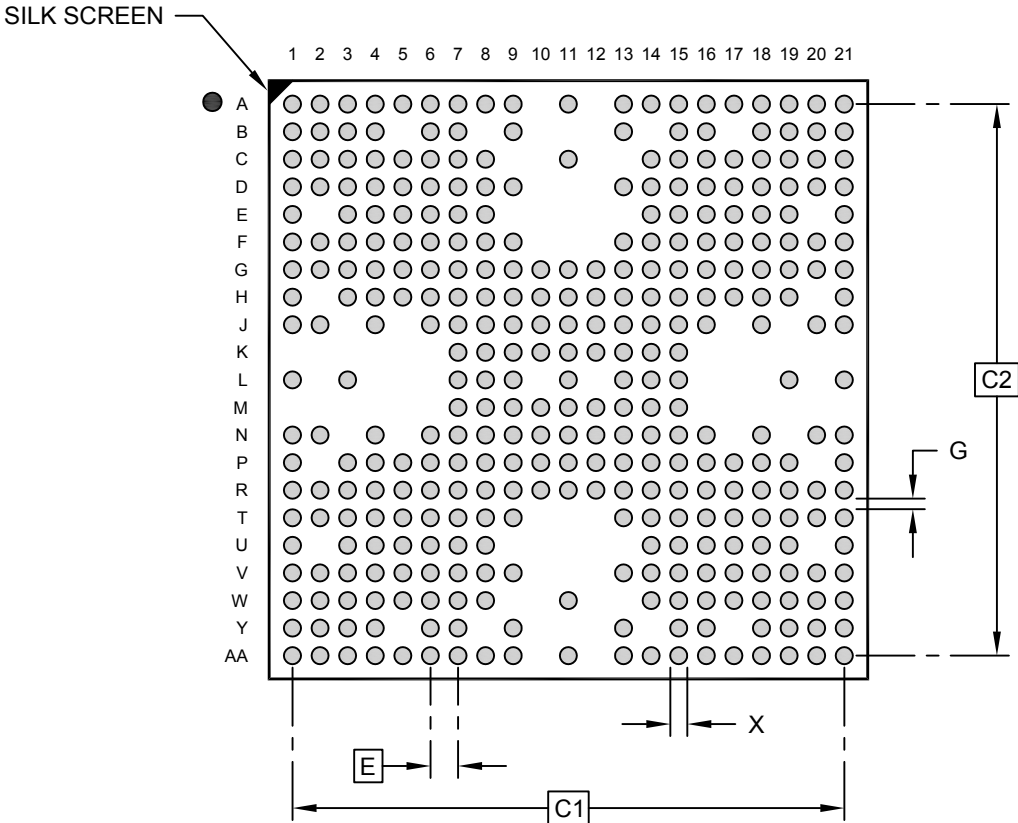


343-Ball Plastic Thin Fine Pitch Ball Grid Array (4HB) - 14x14x1.2 mm Body [TFBGA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

	Units	MILLIMETERS		
		MIN	NOM	MAX
Dimension Limits				
Contact Pitch	E	0.65 BSC		
Contact Pad Spacing	C1		13.00	
Contact Pad Spacing	C2		13.00	
Contact Pad Width (Xnn)	X			0.40
Contact Pad to Contact Pad (Xnn)	G	0.25		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M
 BSC: Basic Dimension. Theoretically exact value shown without tolerances.